



Technical Data

Material:
 Pin(outer sleeve): Brass,machined CuZn38Pb2
 Clip(contact 4 finger): Beryllium
 Copper,Phosphor Bronze heat treated
 Plating(outer sleeve):
 Tin plated:2um/80u" Ni, 5um/200u" Sn
 Gold Plated:2um/80u" Ni,Full gold
 Plating(contact): 2um/80u" Ni, gold or Tin plated
 Insulator(black): Glass filled thermoplastic
 polyester UL94V-0

Electrical:
 Current rating: 3Amps/contact max.
 Contact resistance: ≤4mΩ/contact
 Insulation resistance: ≥1000MΩ at V=100V
 Operating voltage: 60VAC/DC

Mechanical:
 Average insertion force with steel pin of
 Ø0.43mm/0.17": <250g
 Average withdrawal force with steel pin of
 Ø0.43mm/0.17": >50g min.
 Mechanical life cycle:min.200
 Operating temperatures:
 Gold Plsted:-55°C to+105°C
 Tin plated:-40°C to+105°C
 Soldering temperature: +240°C,10s max.

How To Order

- RI - (1)(2)/(3) - (4)/(5)
 (1) No. of contact (2) P : Plug S : Socket
 (3) 1 : Single Row/2 : Double Row/3 : 0.3" Row to Row Pitch/
 4 : 0.4" Row to Row Pitch/6 : 0.6" Row to Row Pitch
 (4) Contact Plating
 GF : Gold Flash/T200 : Tin 200 μ"/SG : Select Gold Flash/
 S10 : Select Gold plated 10 μ"/S15 : Select Gold plated
 15 μ"/S30 : Select Gold plated 30 μ"
 (5) Blanked : Dip Solder Type/W : Wire Wrapping/D : SMD Type
 E : Empty , No Bar
 Ex. RI - 32S/6 - SG/E
 Round IC Socket 32Pin , Socket /0.6" Row to Row Pitch
 Select Gold Flash /Empty , No Bar (Dip Solder Type)
 Ex. RI - 40S/6 - SG
 Round IC Socket 40Pin/Socket /0.6" Row to Row Pitch/
 Select Gold Flash

No. of Positions	DIM"A"	DIM"B"
24	30.48	27.94
28	35.56	33.02
32	40.64	38.10
40	50.80	48.26
42	53.34	50.80
48	60.96	58.42

				TOLERANCES ARE		APPROVED		DATE		DRAWING NO	
				X.	±0.25						
				X.X	±0.1	CHECKED		DATE		NAME	
				X.XX	±0.01						
				X.XXX	±0.005	DRAWN		DATE		UNIT	
				X.XXXX	±0.002	Lee		2006/06/02		MM	
△	新圖發行	Lee	2006-06-02			SCALE		REV			
SER	REVISIONS	CHK	DATE			1:1		A			